



SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

- Samsung P/N : [CL31C681JHHNNNF](#)
- Description : [CAP, 680pF, 630V, ±5%, C0G, 1206](#)

A. Samsung Part Number

CL 31 C 681 J H H N N N F
 ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Series	Samsung Multi-layer Ceramic Capacitor									
② Size	1206 (inch code)			L: 3.2 ± 0.2 mm			W: 1.6 ± 0.2 mm			
③ Dielectric	C0G	⑧ Inner electrode	Ni							
④ Capacitance	680 pF	⑨ Termination	Cu							
⑤ Capacitance tolerance	±5 %	⑩ Plating	Sn 100% (Pb Free)							
⑥ Rated Voltage	630 V	⑪ Product	Normal							
⑦ Thickness	1.6 ± 0.2 mm	⑫ Special	Reserved for future use							
		⑬ Packaging	Embossed Type, 13" reel							

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition	
Capacitance	Within specified tolerance	1MHz±10%	0.5~5Vrms
Q	1000 min		
Insulation Resistance	10,000Mohm or 500Mohm·μF Whichever is Smaller	500±50 Vdc	60~120 sec.
Appearance	No abnormal exterior appearance	Microscope (×10)	
Withstanding Voltage	No dielectric breakdown or mechanical breakdown	150% of the rated voltage	
Temperature Characterisitcs	C0G (From -55 °C to 125 °C, Capacitance change shoud be within ±30PPM/°C)		
Adhesive Strength of Termination	No peeling shall be occur on the terminal electrode	500g·F, for 10±1 sec.	
Bending Strength	Capacitance change : within ±5% or ±0.5pF whichever is larger	Bending to the limit (1mm) with 1.0mm/sec.	
Solderability	More than 75% of terminal surface is to be soldered newly	SnAg3.0Cu0.5 solder 245±5 °C, 3±0.3sec. (preheating : 80~120 °C for 10~30sec.)	
Resistance to Soldering heat	Capacitance change : within ±2.5% or ±0.25pF whichever is larger Tan δ, IR : initial spec.	Solder pot : 270±5 °C, 10±1sec.	

	Performance	Test condition
Vibration Test	Capacitance change : within $\pm 2.5\%$ or $\pm 0.25\text{pF}$ whichever is larger Tan δ , IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours \times 3 direction (x, y, z)
Moisture Resistance	Capacitance change : within $\pm 7.5\%$ or $\pm 0.75\text{pF}$ whichever is larger Q : 200 min IR : 500Mohm or $25\text{Mohm} \cdot \mu\text{F}$ Whichever is Smaller	With rated voltage 40 $\pm 2^\circ\text{C}$, 90~95%RH, 500+12/-0hrs
High Temperature Resistance	Capacitance change : within $\pm 3\%$ or $\pm 0.3\text{pF}$ whichever is larger Q : 350 min IR : 1000Mohm or $50\text{Mohm} \cdot \mu\text{F}$ Whichever is Smaller	With 120% of the rated voltage Max. operating temperature 1000+48/-0hrs
Temperature Cycling	Capacitance change : within $\pm 2.5\%$ or $\pm 0.25\text{pF}$ whichever is larger Tan δ , IR : initial spec.	1 cycle condition Min. operating temperature $\rightarrow 25^\circ\text{C}$ \rightarrow Max. operating temperature $\rightarrow 25^\circ\text{C}$ 5 cycle test

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^\circ\text{C}$, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.